

REMARKS

In response to the outstanding Office Action:

Restriction. Claims 43-44 are withdrawn, but depend from §102-rejected claim 34, which is argued for below. Should claim 34 be allowed, then claims 43 and 44 should be reinstated and allowed. The new Office Action states that claims 50-52 are also withdrawn. These claims also depend from rejected claims 33 or 34 and should be reinstated and allowed if claim 33 is allowed.

Drawing. The drawing was objected to on the basis of the specification. The specification is amended in view of the Examiner's remarks. Withdrawal of the objection is requested.

§ 102, Tanaka. Claims 33 and 34 were rejected over Tanaka JP '530. This rejection is respectfully traversed.

(1) The Examiner states that Tanaka's element 1 anticipates the claimed tape carrier. However, the Tanaka abstract refers to element 1 as a “mounting board” and the abstract begins, “To improve the mounting density of a semiconductor chip *compared with* ... a tape carrier package ...” (emphasis added). This is seen to imply that what Tanaka discloses is not a tape carrier package, but something else, something to which a tape carrier is compared.

(2) The Examiner also refers to a longitudinal extension disclosed by Tanaka, but none is seen; only a mounting board 1 that is either square (Fig. 1) or rectangular (Fig. 4), depending on the shape of the chip. This disclosure is believed not to reach the second paragraph of claim 33.

(3) The mounting board has a central “opening” 3, in the middle of which is suspended the chip 4. With respect, the chip is not “mounted on” anything, as claim 33 recites.

(4) The Examiner points to Fig. 3(b), which shows a stack made of the item shown being formed in Fig. 3(a); Fig. 3(a) in turn appears to show the structure of Fig. 4 with the wirings 2 folded under. Even if element 1 were indeed a tape carrier (not admitted), Fig. 3(b) still would not show a tape carrier with a first and a second semiconductor element mounted on it; it would show two tape carriers, each with a single semiconductor element mounted respectively on it.

(5) The Examiner asserts that Fig. 3(b) shows a long lead 2 on the top and a short lead 2 on the bottom. With respect, the Examiner misconstrues the reference. As is noted above, Fig. 3(b) shows two stacked assemblies, each with the same lead structure. The Examiner has presented no support for his interpretation of long and short leads, either by citation or argument.

The Examiner is invited to consider:

a) In Fig. 3(b), on the right-hand side, there is a discontinuity in the diagonal cross-hatching of the two leads 2, which shows that the upper lead is bent under the upper mounting board 1, rather than continuing downward alongside the lower mounting board 1. Thus, it has the same shape as the lower lead 2.

b) The lowermost assembly in Fig. 3(b), which is connected to the stack of two assemblies above it by dotted vertical lines, indicates that the stack includes an arbitrary number of assemblies, only two of which are shown at the top. The figure also shows that a single assembly (for example, the one at the bottom of the figure) is part of the stack. Therefore, the stack is a stack of individual, separable assemblies, each including a respective mounting board, respective chip, and respective bend-under leads.

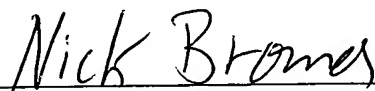
Thus, there is no disclosure of short leads and long leads in Fig. 3(b).

(6) Re claim 34, the chips 4 of applied Fig. 3(b) are not "on" one another as is claimed. They can at best be described as being "above" one another.

On the basis of the arguments above, the Applicants respectfully request allowance of claims 33 and 34, and reinstatement and allowance of their dependent withdrawn claims 43, 44, and 50-52.

Respectfully submitted,

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